

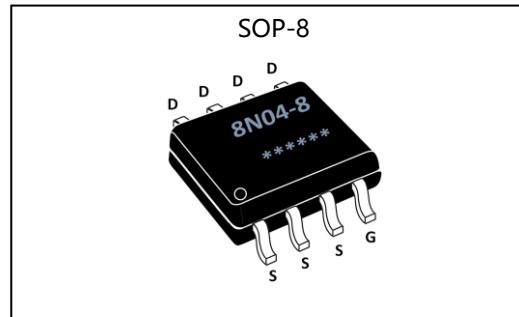
**GL Silicon N Channel Power MOSFET****General Description:**

The GL8N04-8 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications. The package form is SOP-8, which accords with the RoHS standard.

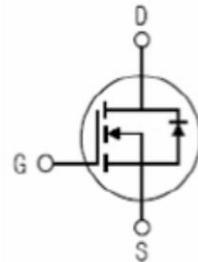
$V_{DSS}$	40	V
$I_D$	8	A
$P_D$	2	W
$R_{DS(ON)type}$	18	$m\Omega$

**Features:**

- $R_{DS(ON)} < 22m\Omega$  @  $V_{GS}=10V$  (Typ18mΩ)
- High density cell design for ultra low  $R_{ds(on)}$
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

**Applications:**

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

**Inner Equivalent Principium Chart****Absolute (Tc= 25°C unless otherwise specified):**

Symbol	Parameter	N-Channel	Units
$V_{DSS}$	Drain-to-Source Voltage	40	V
$I_D$	Continuous Drain Current	8	A
$I_{DM}$	Pulsed Drain Current	40	A
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$P_D$	Power Dissipation	2	W
$T_J, T_{stg}$	Operating Junction and Storage Temperature Range	-55 to 150	°C



## GL Silicon N Channel Power MOSFET

Electrical Characteristics (Tc= 25°C unless otherwise specified):

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V <sub>DSS</sub>	Drain to Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	40	--	--	V
I <sub>DSS</sub>	Drain to Source Leakage Current	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V, T <sub>a</sub> =25°C	--	--	1.0	μA
I <sub>GSS(F)</sub>	Gate to Source Forward Leakage	V <sub>GS</sub> =+10V	--	--	0.1	μA
I <sub>GSS(R)</sub>	Gate to Source Reverse Leakage	V <sub>GS</sub> =-10V	--	--	-0.1	μA

ON Characteristics <sup>a3</sup>						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
R <sub>DSON</sub>	Drain-to-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =8A	--	17	22	mΩ
V <sub>GTH</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	1.5	2.5	V
Pulse width tp≤380μs, δ≤2%						

Dynamic Characteristics <sup>a4</sup>						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =15V, I <sub>D</sub> =8A	3	--	--	S
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =20V	--	415	--	pF
C <sub>oss</sub>	Output Capacitance	f=1.0MHz	--	115	--	
C <sub>rss</sub>	Reverse Transfer Capacitance		--	11	--	

Resistive Switching Characteristics <sup>a4</sup>						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> =15V, R <sub>L</sub> =2.5Ω	--	4.5	--	ns
t <sub>r</sub>	Rise Time		--	3.0	--	
t <sub>d(OFF)</sub>	Turn-Off Delay Time		--	14.5	--	
t <sub>f</sub>	Fall Time		--	3.0	--	
Q <sub>g</sub>	Total Gate Charge	V <sub>DD</sub> =20V, I <sub>D</sub> =8A	--	12	--	nC
Q <sub>gs</sub>	Gate to Source Charge		--	3.2	--	
Q <sub>gd</sub>	Gate to Drain ( "Miller" )Charge		--	3.1	--	



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Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I <sub>S</sub>	Continuous Source Current <sup>a2</sup> (Body Diode)		--	--	8	A
V <sub>SD</sub>	Diode Forward Voltage <sup>a3</sup>	I <sub>S</sub> =8A, V <sub>GS</sub> =0V	--	--	1.5	V

Symbol	Parameter	Typ.	Units
R <sub>θJA</sub>	Junction-to-Ambient	62.5	°C/W

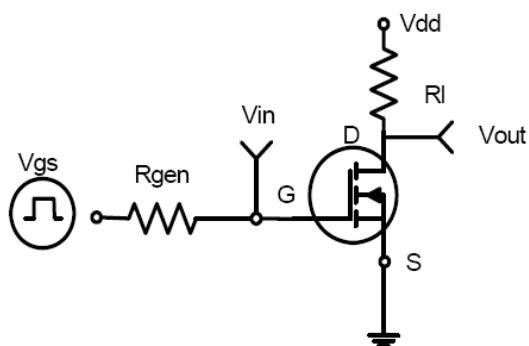
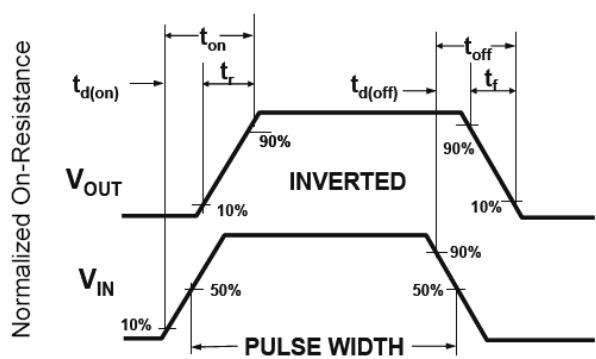
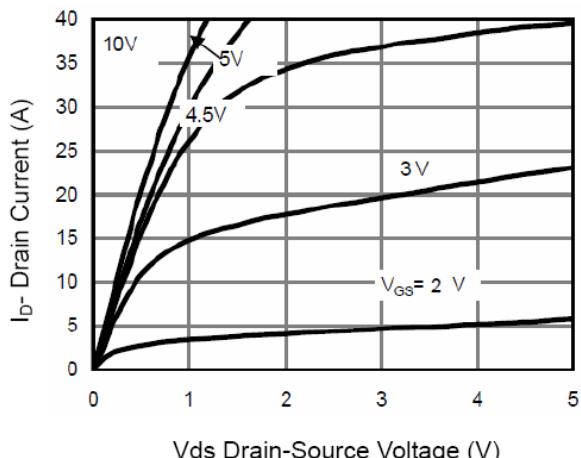
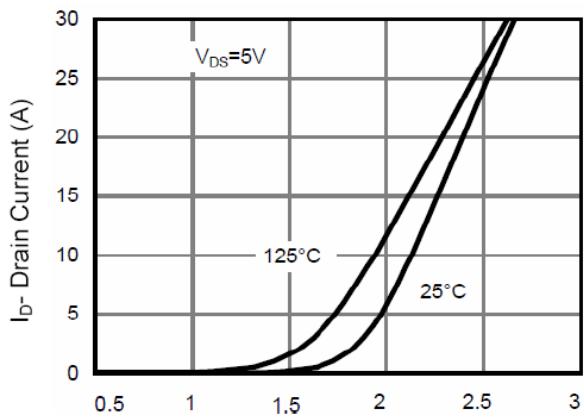
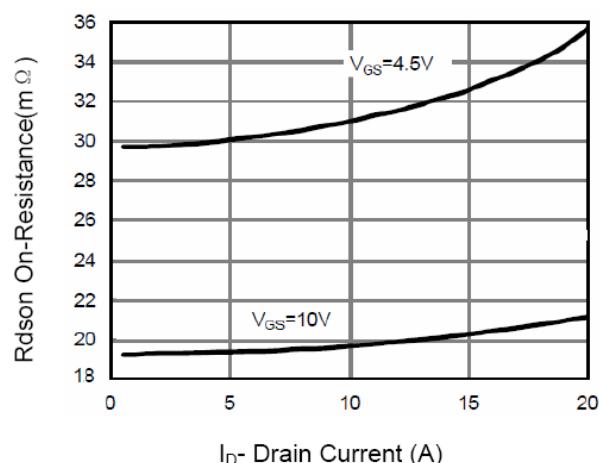
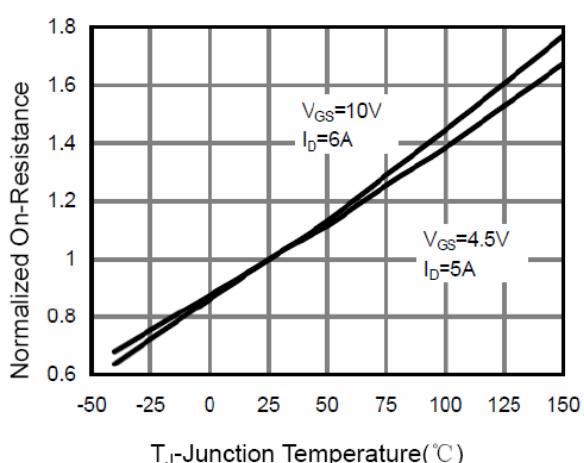
<sup>a1</sup>: Repetitive Rating: Pulse width limited by maximum junction temperature.

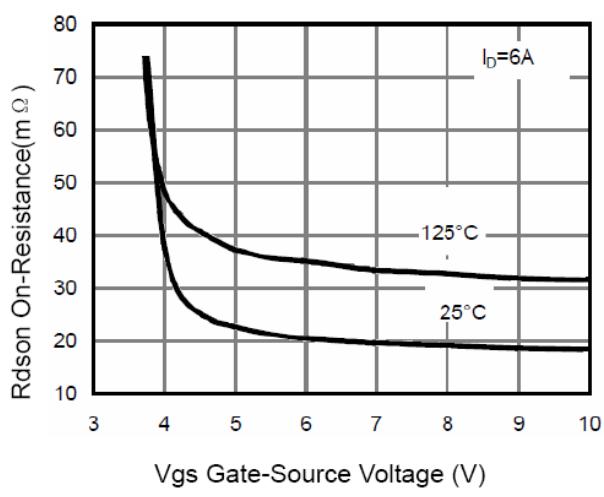
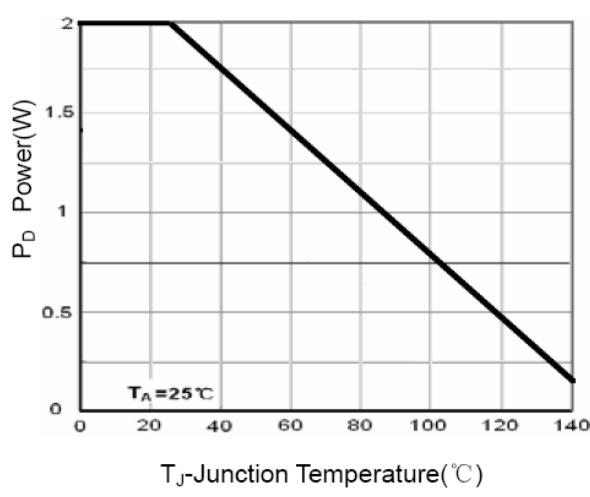
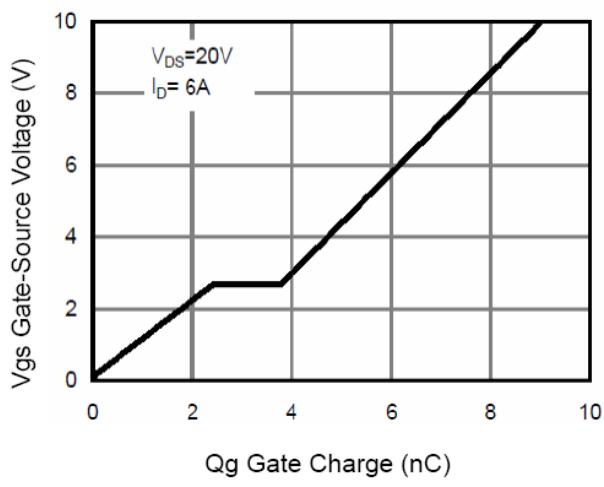
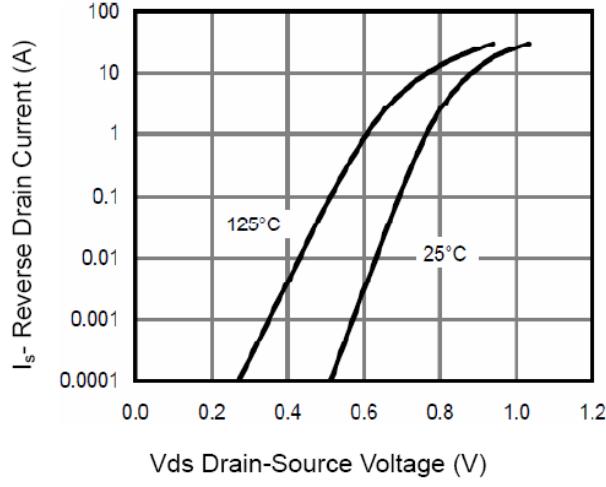
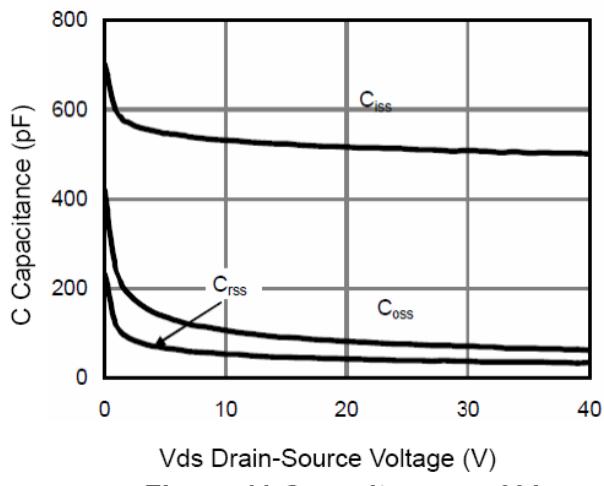
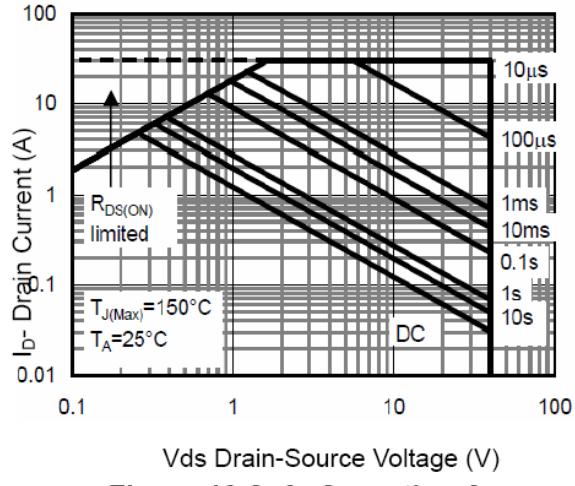
<sup>a2</sup>: Surface Mounted on FR4 Board, t≤10sec.

<sup>a3</sup>: Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%.

<sup>a4</sup>: Guaranteed by design, not subject to production

<sup>a5</sup>: EAS condition: T<sub>j</sub>=25°C, V<sub>DD</sub>=15V, V<sub>GS</sub>=10V, L=1.0mH, R<sub>g</sub>=25Ω

**GL Silicon N Channel Power MOSFET**
**Characteristics Curve:**

**Figure 1:Switching Test Circuit**

**Figure 2:Switching Waveforms**

**Figure 3 Output Characteristics**

**Figure 4 Transfer Characteristics**

**Figure 5 Drain-Source On-Resistance**

**Figure 6 Drain-Source On-Resistance**

**GL Silicon N Channel Power MOSFET**

**Figure 7 Rdson vs Vgs**

**Figure 8 Power Dissipation**

**Figure 9 Gate Charge**

**Figure 10 Source- Drain Diode Forward**

**Figure 11 Capacitance vs Vds**

**Figure 12 Safe Operation Area**

## GL Silicon N Channel Power MOSFET

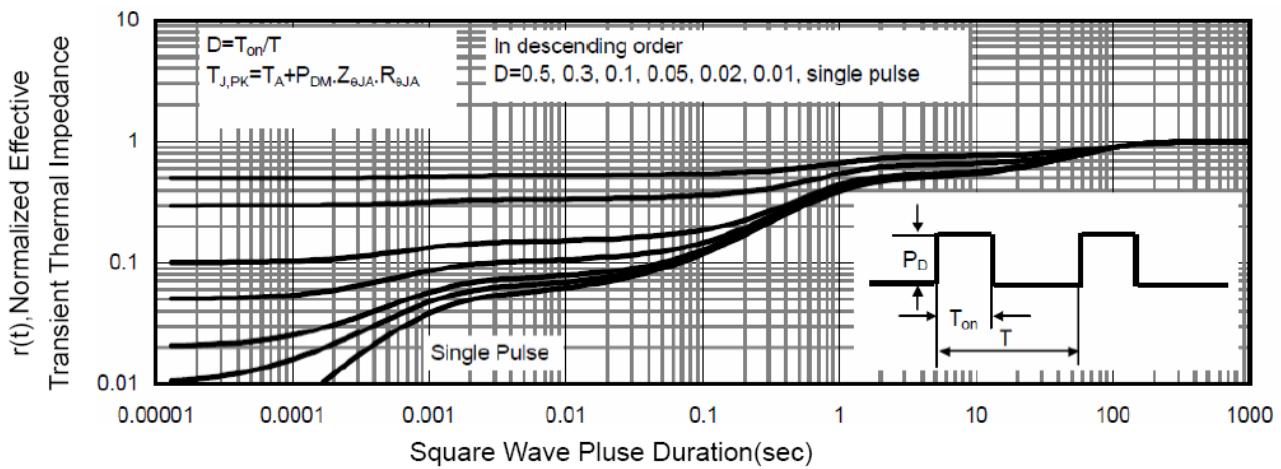


Figure 13 Normalized Maximum Transient Thermal Impedance

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